

**ZXMP4A57E6**

**40V P-CHANNEL ENHANCEMENT MODE MOSFET**

**Product Summary**

| $V_{(BR)DSS}$ | $R_{DS(on)}$ max                 | $I_D$ max<br>$T_A = 25^\circ C$ |
|---------------|----------------------------------|---------------------------------|
| -40V          | 80m $\Omega$ @ $V_{GS} = -10V$   | -3.7 A                          |
|               | 150m $\Omega$ @ $V_{GS} = -4.5V$ | -2.8 A                          |

**Description and Applications**

This MOSFET has been designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

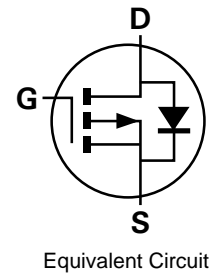
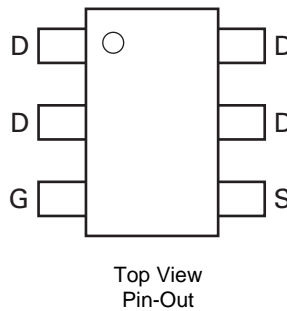
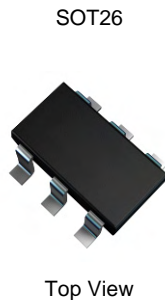
- Motor control
- DC-DC Converters
- Power management functions
- Uninterrupted power supply

**Features and Benefits**

- Fast switching speed
- Low gate drive
- Low input capacitance
- "Lead Free", RoHS Compliant (Note 1)
- Halogen and Antimony Free. "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

**Mechanical Data**

- Case: SOT26
- Case Material: Molded Plastic, UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin annealed over Copper lead frame. Solderable per MIL-STD-202, Method 208
- Weight 0.018 grams (approximate)

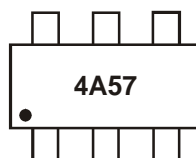


**Ordering Information** (Note 3)

| Product      | Marking | Reel size (inches) | Tape width (mm) | Quantity per reel |
|--------------|---------|--------------------|-----------------|-------------------|
| ZXMP4A57E6TA | 4A57    | 7                  | 8               | 3,000             |

- Notes:
1. No purposefully added lead
  2. Diodes Inc's "Green" policy can be found on our website at <http://www.diodes.com>.
  3. For packaging details, go to our website at <http://www.diodes.com>.

**Marking Information**



4A57 = Product Type Marking Code

**Maximum Ratings** @ $T_A = 25^\circ\text{C}$  unless otherwise specified

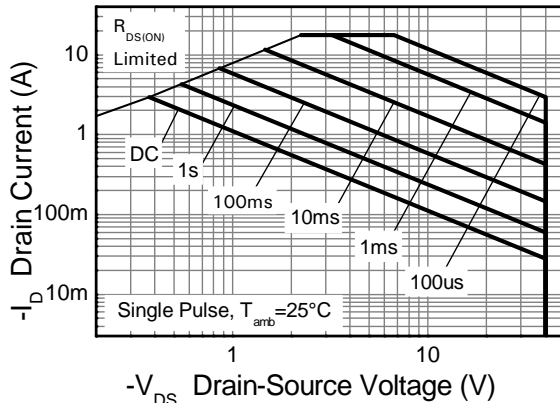
| Characteristic                         |                       |                                   | Symbol    | Value    | Unit |   |
|--|-----------------------|-----------------------------------|-----------|----------|------|---|
| Drain-Source voltage                   |                       |                                   | $V_{DSS}$ | -40      | V    |   |
| Gate-Source voltage                    |                       |                                   | $V_{GS}$  | $\pm 20$ | V    |   |
| Continuous Drain current               | $V_{GS} = 10\text{V}$ | (Note 5)                          | $I_D$     | -3.7     | A    |   |
|  |                       | $T_A = 70^\circ\text{C}$ (Note 5) |           | -2.9     |      |   |
|  |                       | (Note 4)                          |           | -2.9     |      |   |
| Pulsed Drain current                   | $V_{GS} = 10\text{V}$ | (Note 6)                          | $I_{DM}$  | -18      | A    |   |
| Continuous Source current (Body diode) |                       |                                   | (Note 5)  | $I_S$    | -2.6 | A |
| Pulsed Source current (Body diode)     |                       |                                   | (Note 6)  | $I_{SM}$ | -18  | A |

**Thermal Characteristics** @ $T_A = 25^\circ\text{C}$  unless otherwise specified

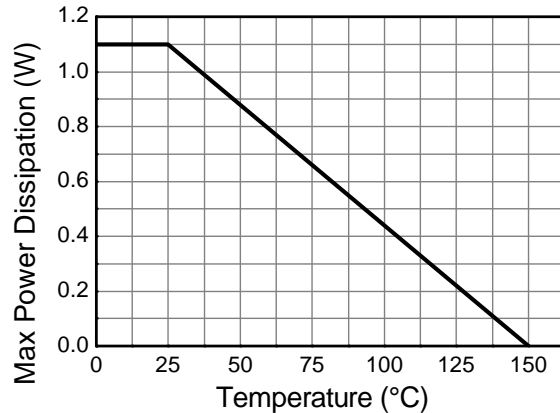
| Characteristic                          |          | Symbol          | Value      | Unit                       |
|---|----------|-----------------|------------|----------------------------|
| Power dissipation                       | (Note 4) | $P_D$           | 1.1        | W                          |
|   |          |                 | 8.8        |                            |
| Linear derating factor                  | (Note 5) |                 | 1.7        | $\text{mW}/^\circ\text{C}$ |
|   |          |                 | 13.7       |                            |
| Thermal Resistance, Junction to Ambient | (Note 4) | $R_{\theta JA}$ | 113        | $^\circ\text{C}/\text{W}$  |
|   | (Note 5) |                 | 73         |                            |
| Operating and storage temperature range |          | $T_J, T_{STG}$  | -55 to 150 | $^\circ\text{C}$           |

- Notes:
4. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
  5. Same as note (4), except the device is measured at  $t \leq 5$  sec.
  6. Same as note (4), except the device is pulsed with  $D = 0.02$  and pulse width 300 $\mu\text{s}$ . The pulse current is limited by the maximum junction temperature.

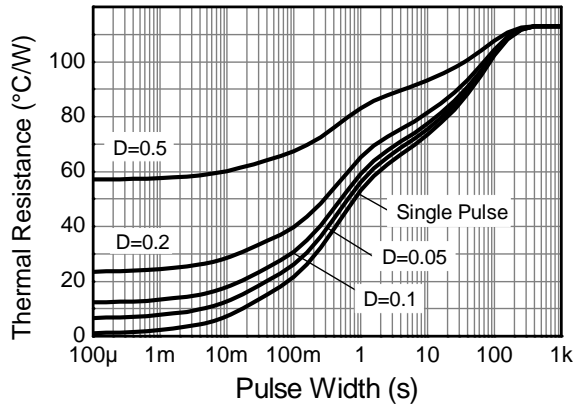
**Thermal Characteristics**



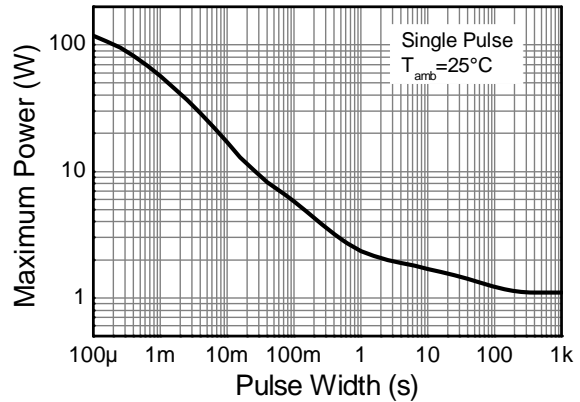
**P-channel Safe Operating Area**



**Derating Curve**



**Transient Thermal Impedance**



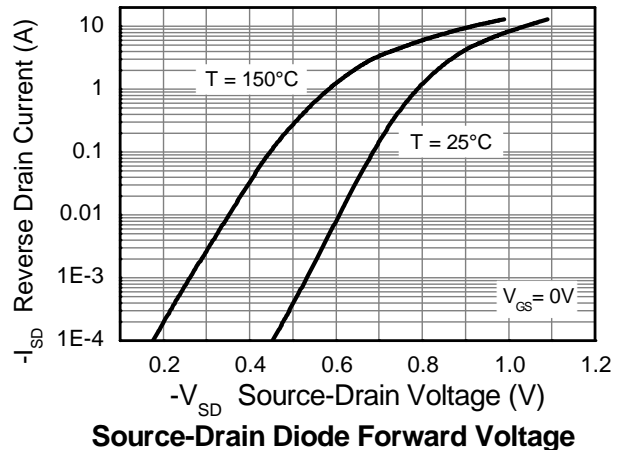
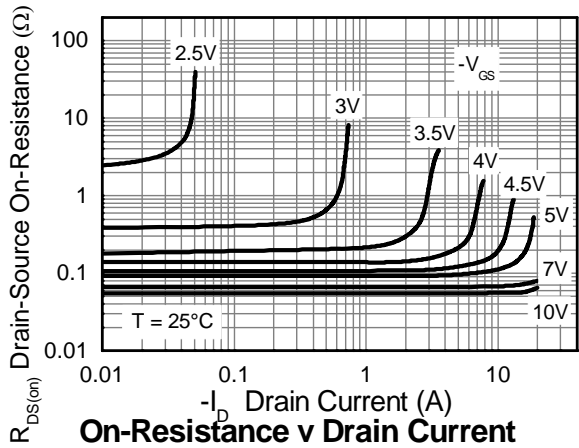
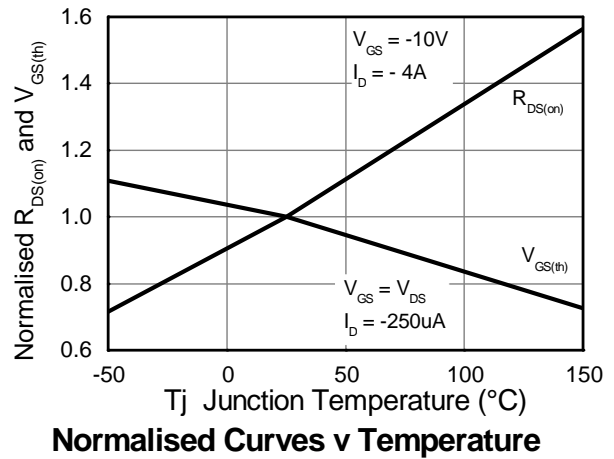
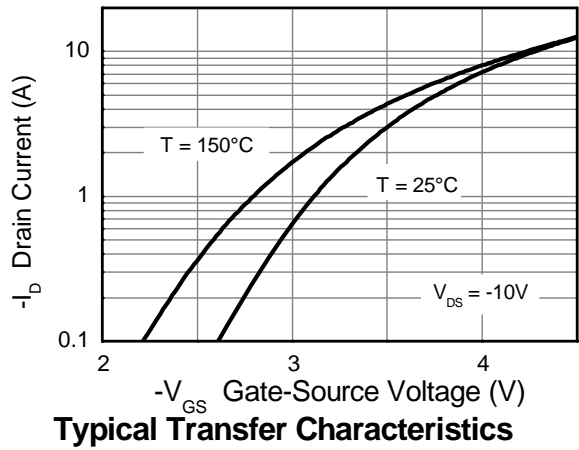
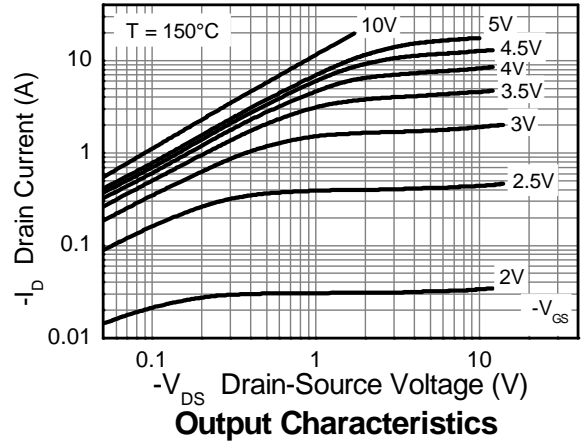
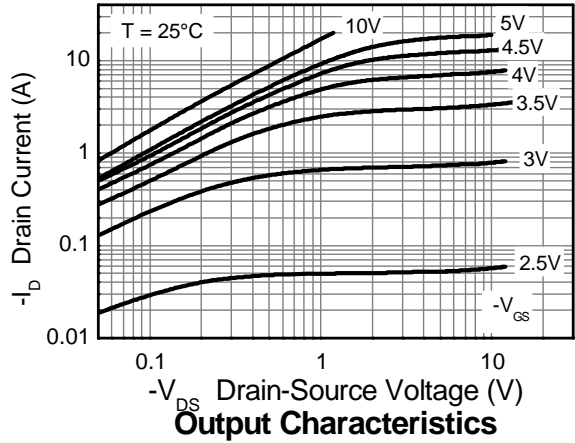
**Pulse Power Dissipation**

**Electrical Characteristics** @ $T_A = 25^\circ\text{C}$  unless otherwise specified

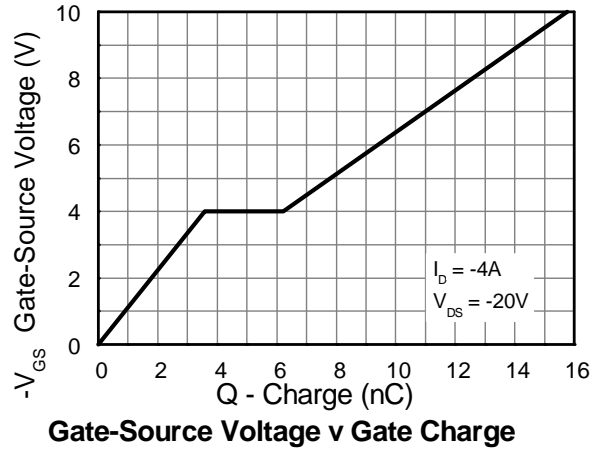
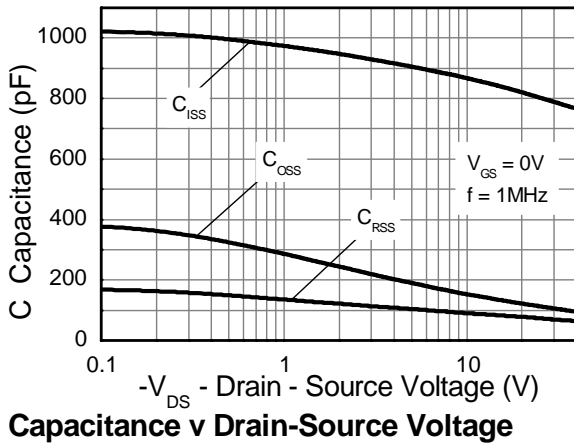
| Characteristic                             | Symbol       | Min  | Typ   | Max       | Unit          | Test Condition  |
|--|--------------|------|-------|-----------|---------------|---|
| <b>OFF CHARACTERISTICS</b>                 |              |      |       |           |               |   |
| Drain-Source Breakdown Voltage             | $BV_{DSS}$   | -40  | —     | —         | V             | $I_D = -250\mu\text{A}, V_{GS} = 0\text{V}$   |
| Zero Gate Voltage Drain Current            | $I_{DSS}$    | —    | —     | -0.5      | $\mu\text{A}$ | $V_{DS} = -40\text{V}, V_{GS} = 0\text{V}$  |
| Gate-Source Leakage                        | $I_{GSS}$    | —    | —     | $\pm 100$ | nA            | $V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$   |
| <b>ON CHARACTERISTICS</b>                  |              |      |       |           |               |   |
| Gate Threshold Voltage                     | $V_{GS(th)}$ | -1.0 | —     | -3.0      | V             | $I_D = -250\mu\text{A}, V_{DS} = V_{GS}$  |
| Static Drain-Source On-Resistance (Note 7) | $R_{DS(on)}$ | —    | —     | 0.080     | $\Omega$      | $V_{GS} = -10\text{V}, I_D = -4\text{A}$  |
|  |              | —    | —     | 0.150     |               | $V_{GS} = -4.5\text{V}, I_D = -2\text{A}$   |
| Forward Transconductance (Notes 7 & 8)     | $g_{fs}$     | —    | 7.6   | —         | S             | $V_{DS} = -15\text{V}, I_D = -4\text{A}$  |
| Diode Forward Voltage (Note 7)             | $V_{SD}$     | —    | -0.86 | -0.95     | V             | $I_S = -4\text{A}, V_{GS} = 0\text{V}$  |
| Reverse recovery time (Note 8)             | $t_{rr}$     | —    | 17.4  | —         | ns            | $I_S = -1.8\text{A}, di/dt = 100\text{A}/\mu\text{s}$   |
| Reverse recovery charge (Note 8)           | $Q_{rr}$     | —    | 11.1  | —         | nC            |   |
| <b>DYNAMIC CHARACTERISTICS (Note 8)</b>    |              |      |       |           |               |   |
| Input Capacitance                          | $C_{iss}$    | —    | 833   | —         | pF            | $V_{DS} = -20\text{V}, V_{GS} = 0\text{V}$<br>$f = 1\text{MHz}$                                   |
| Output Capacitance                         | $C_{oss}$    | —    | 122   | —         |               |   |
| Reverse Transfer Capacitance               | $C_{rss}$    | —    | 78    | —         |               |   |
| Total Gate Charge (Note 9)                 | $Q_g$        | —    | 7     | —         | nC            | $V_{GS} = -4.5\text{V}$<br>$V_{GS} = -10\text{V}$<br>$V_{DS} = -20\text{V}$<br>$I_D = -4\text{A}$ |
| Total Gate Charge (Note 9)                 | $Q_g$        | —    | 15.8  | —         |               |   |
| Gate-Source Charge (Note 9)                | $Q_{gs}$     | —    | 3.6   | —         |               |   |
| Gate-Drain Charge (Note 9)                 | $Q_{gd}$     | —    | 2.7   | —         |               |   |
| Turn-On Delay Time (Note 9)                | $t_{D(on)}$  | —    | 2.5   | —         | ns            | $V_{DD} = -20\text{V}, V_{GS} = -10\text{V}$<br>$I_D = -1\text{A}, R_G \equiv 6.0\Omega$          |
| Turn-On Rise Time (Note 9)                 | $t_r$        | —    | 3.3   | —         |               |   |
| Turn-Off Delay Time (Note 9)               | $t_{D(off)}$ | —    | 47    | —         |               |   |
| Turn-Off Fall Time (Note 9)                | $t_f$        | —    | 21    | —         |               |   |

- Notes:
7. Measured under pulsed conditions. Pulse width  $\leq 300\mu\text{s}$ ; duty cycle  $\leq 2\%$
  8. For design aid only, not subject to production testing.
  9. Switching characteristics are independent of operating junction temperatures.

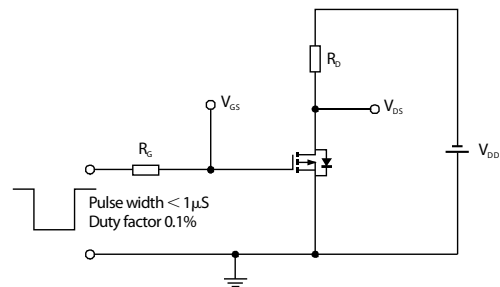
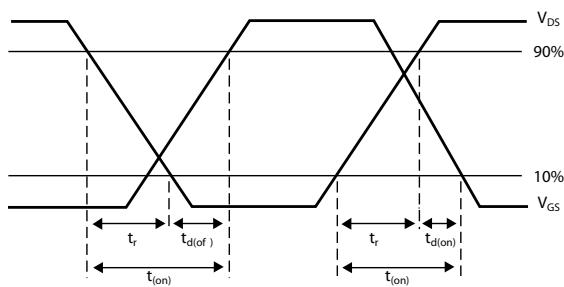
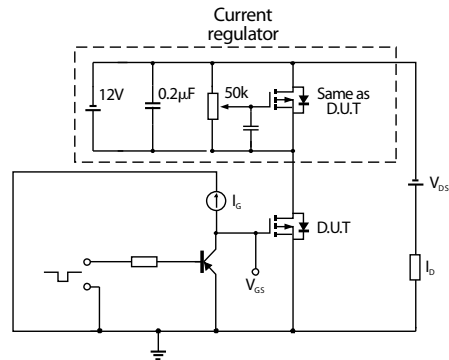
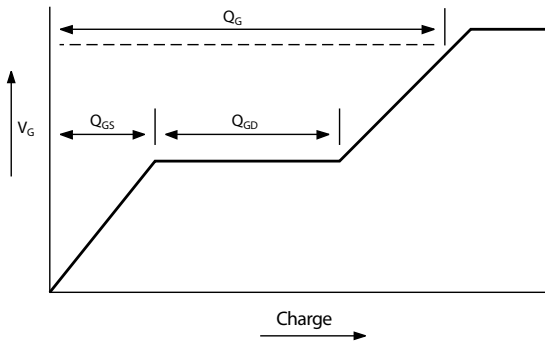
**Typical Characteristics**



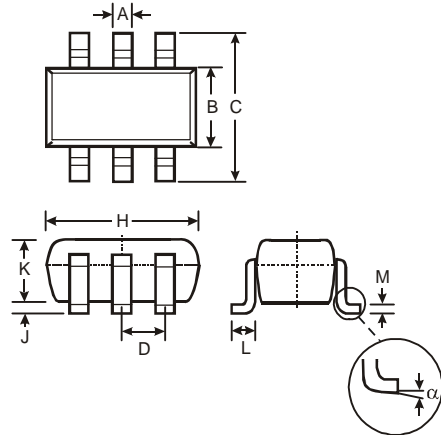
**Typical Characteristics - continued**



**Test Circuits**

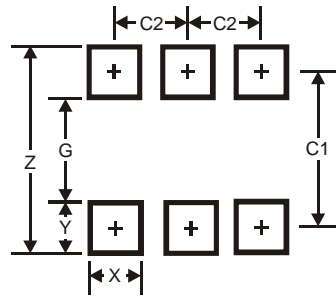


**Package Outline Dimensions**



| SOT-26               |       |      |      |
|----------------------|-------|------|------|
| Dim                  | Min   | Max  | Typ  |
| A                    | 0.35  | 0.50 | 0.38 |
| B                    | 1.50  | 1.70 | 1.60 |
| C                    | 2.70  | 3.00 | 2.80 |
| D                    | —     | —    | 0.95 |
| H                    | 2.90  | 3.10 | 3.00 |
| J                    | 0.013 | 0.10 | 0.05 |
| K                    | 1.00  | 1.30 | 1.10 |
| L                    | 0.35  | 0.55 | 0.40 |
| M                    | 0.10  | 0.20 | 0.15 |
| α                    | 0°    | 8°   | —    |
| All Dimensions in mm |       |      |      |

**Suggested Pad Layout**



| Dimensions | Value (in mm) |
|------------|---------------|
| Z          | 3.20          |
| G          | 1.60          |
| X          | 0.55          |
| Y          | 0.80          |
| C1         | 2.40          |
| C2         | 0.95          |

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